

# N-Channel 150 V (D-S) MOSFET



PRODUCT SUMMARY					
V <sub>DS</sub> (V)	150				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.0079				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 7.5 \text{ V}$	0.0085				
Q <sub>g</sub> typ. (nC)	35.1				
I <sub>D</sub> (A)	77.4				
Configuration	Single				

#### **FEATURES**

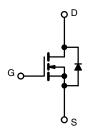
- TrenchFET® Gen V power MOSFET
- Very low R<sub>DS</sub> x Q<sub>g</sub> figure-of-merit (FOM)
- Tuned for the lowest R<sub>DS</sub> x Q<sub>oss</sub> FOM
- 100 % R<sub>a</sub> and UIS tested
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

# RoHS COMPLIANT

**FREE** 

### **APPLICATIONS**

- · Synchronous rectification
- · Primary side switch
- DC/DC converters
- Power supplies
- Motor drive control



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8
Lead (Pb)-free and halogen-free	SiR570DP-T1-RE3

ABSOLUTE MAXIMUM RATING	<b>iS</b> (T <sub>A</sub> = 25 °C, u	nless other	wise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	150	V	
Gate-source voltage		$V_{GS}$	± 20		
	T <sub>C</sub> = 25 °C		77.4		
Continuous dusin assurant /T 150 °C)	T <sub>C</sub> = 70 °C		61.9		
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	19 b, c	1	
	T <sub>A</sub> = 70 °C		15.2 <sup>b, c</sup>	1	
Pulsed drain current (t = 100 μs)		I <sub>DM</sub>	200	A	
Carting and a summer	T <sub>C</sub> = 25 °C		94		
Continuous source-drain diode current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	5.6 <sup>b, c</sup>		
Single pulse avalanche current	l 0.1 mll	I <sub>AS</sub>	30	1	
Single pulse avalanche energy  L = 0.1 m		E <sub>AS</sub>	45	mJ	
	T <sub>C</sub> = 25 °C		104		
Mandan and a super distribution	T <sub>C</sub> = 70 °C		66.6	14/	
Maximum power dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	6.25 <sup>b, c</sup>	W	
	T <sub>A</sub> = 70 °C		4 b, c	Ī	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering recommendations (peak temperature) c		•	260		

THERMAL RESISTANCE RATING	GS				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient <sup>b</sup>	t ≤ 10 s	R <sub>thJA</sub>	15	20	°C/W
Maximum junction-to-case (drain)	Steady state	R <sub>thJC</sub>	0.9	1.2	C/VV

#### **Notes**

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Maximum under steady state conditions is 54 °C/W
- g.  $T_C = 25$  °C

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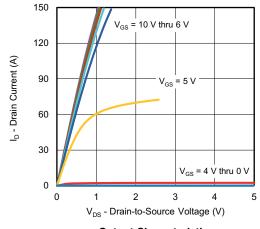
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Static								
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	150	-	-	V		
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 10 mA	-	125	-			
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-6.9	-	mV/°C		
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2	-	4	V		
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	100	nA		
7	,	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V	-	-	1			
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C	-	-	15	μA		
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40	-	-	Α		
Delice and a selection of the selection	_	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	-	- 0.0065 0.0079				
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 15 A	-	0.0070	0.0085	$\Omega$		
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 20 \text{ A}$	-	80	-	S		
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>		-	3740	-	pF		
Output capacitance	C <sub>oss</sub>	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	330	-			
Reverse transfer capacitance	C <sub>rss</sub>		-	6.5	-	-		
Tatal asta shaws	0	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	46.9	71			
Total gate charge	Qg		-	35.1	53	1		
Gate-source charge	Q <sub>gs</sub>	$V_{DS} = 75 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 20 \text{ A}$	-	18.1	-	nC		
Gate-drain charge	$Q_{gd}$		-	4.2	-			
Output charge	Q <sub>oss</sub>	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V	-	111	-	1		
Gate resistance	$R_{g}$	f = 1 MHz	0.4	1.1	1.8	Ω		
Turn-on delay time	t <sub>d(on)</sub>		-	17	34			
Rise time	t <sub>r</sub>	$V_{DD} = 75 \text{ V}, R_1 = 3.75 \Omega, I_D \cong 20 \text{ A},$	-	16	32	1		
Turn-off delay time	t <sub>d(off)</sub>	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	29	58	1		
Fall time	t <sub>f</sub>		-	21	42	1		
Turn-on delay time	t <sub>d(on)</sub>		-	21	42	ns		
Rise time	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_1 = 3.75 \Omega, I_D \cong 20 \text{ A},$	-	74	148			
Turn-off delay time	t <sub>d(off)</sub>	$V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$	-	27	54			
Fall time	t <sub>f</sub>		-	22	44	1		
<b>Drain-Source Body Diode Characteristi</b>	cs		•					
Continuous source-drain diode current	Is	T <sub>C</sub> = 25 °C	-	-	94			
Pulse diode forward current	I <sub>SM</sub>		-	-	200	A		
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> = 5 A, V <sub>GS</sub> = 0 V	-	0.75	1.1	V		
Body diode reverse recovery time	t <sub>rr</sub>		-	84	168	ns		
Body diode reverse recovery charge	Q <sub>rr</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	221	442	nC		
Reverse recovery fall time	t <sub>a</sub>	$T_{\rm J} = 25  ^{\circ}{\rm C}$	-	65	-			
Reverse recovery rise time	t <sub>b</sub>		_	19	_	ns		

#### Notes

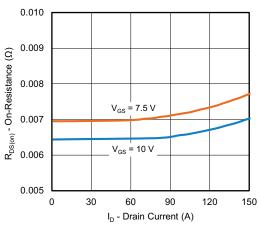
- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

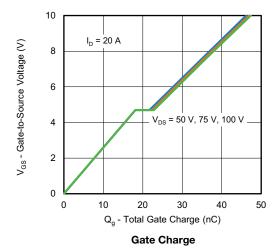


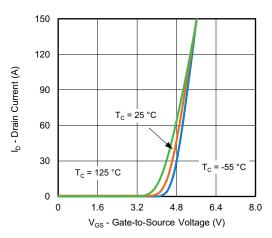


### **Output Characteristics**

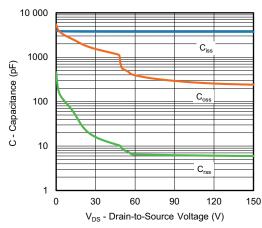


On-Resistance vs. Drain Current and Gate Voltage

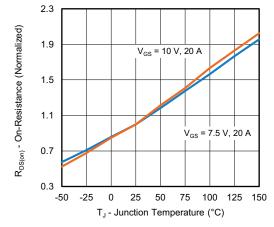




**Transfer Characteristics** 

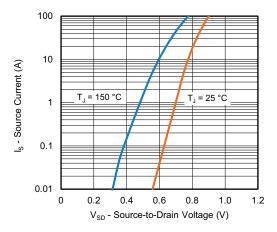


Capacitance

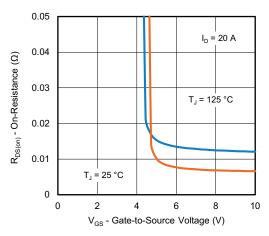


On-Resistance vs. Junction Temperature

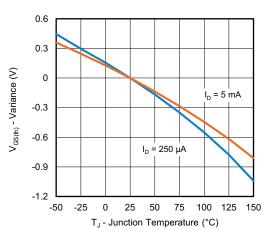




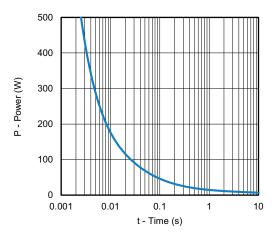
Source-Drain Diode Forward Voltage



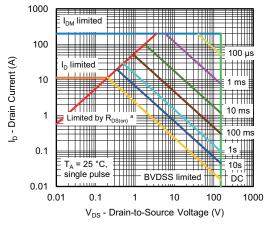
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



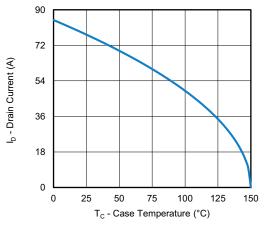
Single Pulse Power, Junction-to-Ambient



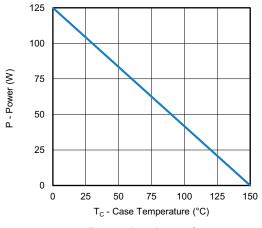
Safe Operating Area, Junction-to-Ambient

#### Note

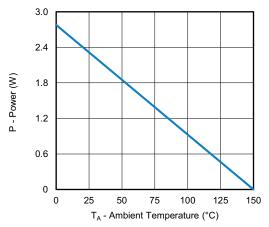
a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



Current Derating a



Power, Junction-to-Case

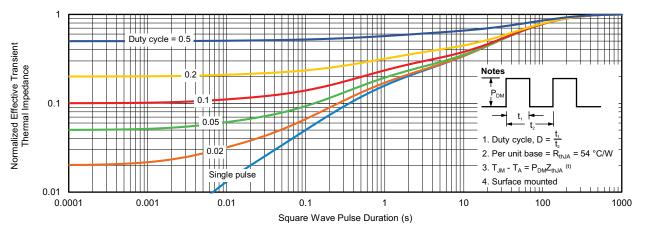


Power, Junction-to-Ambient

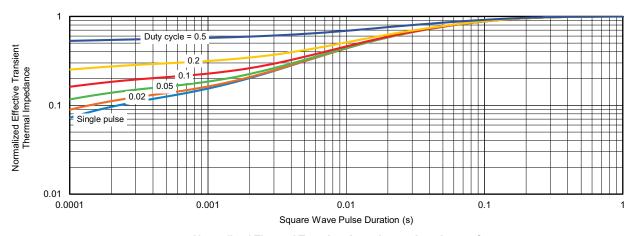
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



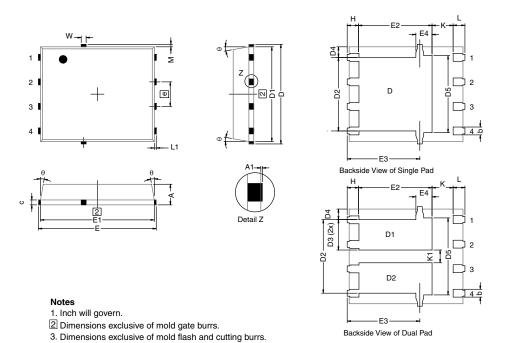
Normalized Thermal Transient Impedance, Junction-to-Case

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DWG: 5881

# PowerPAK® SO-8, (Single/Dual)

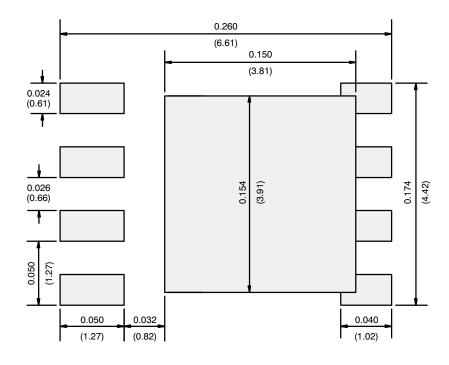


DIM.	MILLIMETERS			INCHES				
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX		
Α	0.97	1.04	1.12	0.038	0.041	0.044		
A1		-	0.05	0	-	0.002		
b	0.33	0.41	0.51	0.013	0.016	0.020		
С	0.23	0.28	0.33	0.009	0.011	0.013		
D	5.05	5.15	5.26	0.199	0.203	0.20		
D1	4.80	4.90	5.00	0.189	0.193	0.19		
D2	3.56	3.76	3.91	0.140	0.148	0.154		
D3	1.32	1.50	1.68	0.052	0.059	0.066		
D4		0.57 typ.			0.0225 typ.			
D5		3.98 typ.			0.157 typ.			
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	5.79	5.89	5.99	0.228	0.232	0.23		
E2	3.48	3.66	3.84	0.137	0.144	0.15		
E3	3.68	3.78	3.91	0.145	0.149	0.154		
E4		0.75 typ.		0.030 typ.				
е		1.27 BSC		0.050 BSC				
K		1.27 typ.		0.050 typ.				
K1	0.56	-	-	0.022	-	=		
Н	0.51	0.61	0.71	0.020	0.024	0.028		
L	0.51	0.61	0.71	0.020	0.024	0.028		
L1	0.06	0.13	0.20	0.002	0.005	0.008		
θ	0°	-	12°	0°	-	12°		
W	0.15	0.25	0.36	0.006	0.010	0.014		
М		0.125 typ.			0.005 typ.			

Revison: 13-Feb-17 1 Document Number: 71655



# RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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